SPECIFICATION FOR APPROVAL

DESCRIPTION: Pitch 0.50mm ZIF FPO	C Connector, R/A, SMT Type Bottom Contact	
CUSTOMER PROD.NO/DWG.NO:		
E&T PROD.NO:	6705K-XXXX-00,20,30,40X	
APPROVAL SHEET NO:		
E&T DWG. NO./DOCUMENT:	6705K-XXXX-00,20,30,40X	
		DEV: AA

PLEASE RETURN TO US ONE COPY OF SPECIFICATION FOR APPROVAL WITH YOUR APPROVED SIGNATURES.

APPROVED SIGNATURES							



ENTERY INDUSTRIAL CO., LTD.
E&T ELECTRONICS (DONG GUAN) CO., LTD.
E&T ELECTRONICS (SU ZHOU) CO., LTD.

Title: Pitch 0.50mm ZIF FPC Connector, R/A, SMT Type Bottom Contact

REN20140501 Title: Pitch			0.50mm ZIF FPC Connector, R/A, SMT Type Bottom Contact				
A4	05.15,2012	This l	This Document Contains Information That Is Proprietary To				
Rev	Description	E&T	And Should Not Be Used Without Wi	ritten Permission			
Document No.			Prepared By: Hill Chang	Date:03,31,2009'			
6705K-XXXX-00,20,20,40X),20,20,40X	Checked By:	Date: of of za/o			
ľ			Approved By:	Date:			

GROUP AND TEST SEQUENCE

	Tost of Evamination		Test Group									
Test of Examination		A	В	С	D	Е	F	G	Н	I	J	K
1	Examination of Product	1,9	1,6	1,5	1,5	1,5	1,4	1,5	1,3	1,3	1,5	
2	Contact Resistance	2,6	2,5	2,4	2,4	2,4		2,4			2,4	
3	Insulation Resistance	3,7										
4	Dielectric Strength	4,8										
5	FPC Retention Force		3									
6	Terminal / Housing Retention Force											1
7	Durability		4									
8	Vibration			3								
9	Heat Resistance				3							
10	Cold Resistance					3						
11	Humidity	5										
12	Solder Ability						3		2			
13	Resistance To Soldering Heat									2		
14	Steam Aging						2					
15	Salt Spray							3				
16	Temperature Cycling										3	

PRODUCT SPECIFICATION

1. SCOPE:

This specification covers the pitch 0.50 mm ZIF FPC connector series.

2. PRODUCT NAME AND PART NUMBER:

Product Name	E&T Part Number
0.50mm ZIF FPC Connector, R/A, SMT Type Bottom Contact	6705K-XXXX-00,20,30,40X

3. RATINGS:

Item	Standard		
Rated Voltage (MAX.)	50 V	(AC(rms/DC)	
Rated Current (MAX.)	0.5A	(AC(IIIIS/DC)	
Operating Temperature Range	-40°	C ~ +85 ⁰ C	

^{*}Including terminal temperature rise

4.PERFORMANCE:

4- 1 Electrical Performance

	Item	Test Condition	Requirement
4-1-1	Contact Resistance	Test Current: 10 mA Max. Test Voltage: 20mV Max Test Method: EIA-364-06B	20 mΩ MAX.
4-1-2	Insulation Resistance	Test Voltage: 500V DC. Test Duration: 1 minutes. Test Method: EIA-364-21C	100 MΩ Min.
4-1-3	Dielectric Strength	Test Voltage:500V AC. Test Time: 60 sec. Test Method: EIA-364-20B	No Breakdown

4-2 Mechanical Performance

	Item	Test Condition	Requirement	
4-2-1	FPC Retention Force	Test Speed: 25±3 mm/min. Test Method: EIA-364-29B	Refer to pa	aragraph 6
4-2-2	Terminal / Housing Retention Force	Test Speed: 25mm/min.	0.1kgf (Min)	
		Insert and withdraw actuator up to	Contact R	esistance
4-2-3	Durability	20cycles at the speed rate of less than 10 cycles/	Initial Value	$\leqq 20 \text{ m}\Omega$
		minute. Test Method: EIA-364-09C	Final Value	≤40 mΩ

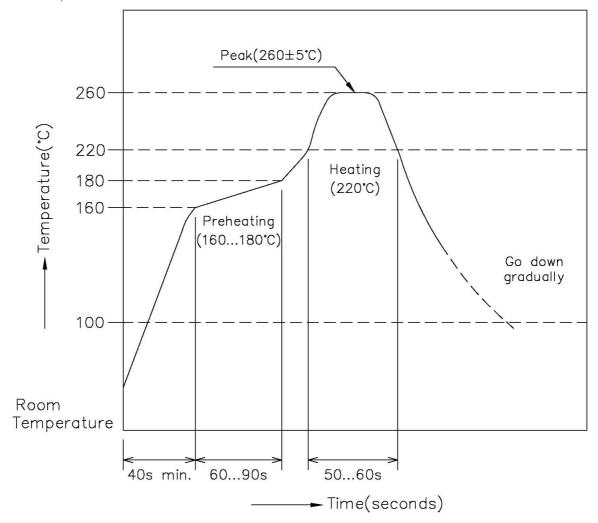
4-3 Environmental Performance and Others

	Item	Test Condition	Require	ment
		Amplitude : 1.5 ₪₪ Frequency range: 10~55~10 Hz in 1 minute	Appearance	No Damage
4-3-1	Vibration	Duration: 2 hours in each X.Y.Z axes Current: 100mA. Test Method: EIA-364-28D	Contact Resistance	≦40 mΩ
		Test Method. EIA-304-20D	Discontinuity	1µsec
4-3-2	Heat	Temperature: 85±2°ℂ at Duration: 96 hours		No Damage
4-5-2	Resistance		Contact Resistance	≦40 mΩ
4-3-3	Cold	Temperature: -40±2°C Duration: 96 hours	Appearance	No Damage
4-0-0	Resistance		Contact Resistance	≤40 mΩ
		Temperature: 40±2℃ Relative Humidity: 90~95%	Appearance	No Damage
4-3-4	Humidity	Duration: 96 hours Test Method: EIA-364-31B	Contact Resistance	≤40 mΩ
1-5-4	Trairiidity		Insulation Resistance	\geq 100M Ω
			Dielectric Strength	Must meet 4-1-3

	Item	Test Condition	Requir	rement	
4-3-5	Solder Ability	Soldering Time : 3±0.5 sec Solder Temperature : 245±5°ℂ Test Method: EIA-364-52		Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-6	Resistance To Soldering Heat	Soldering Time : 10±0.5 sec Solder Temperature : 260±5℃ Test Method: EIA-364-56C		Appearance	No Damage
		Steam Aging Temperature : 98± Duration: 8 hours Solder Temperature : 245±5°C	2℃	Appearance	No Damage
4-3-7	Steam Aging	Soldering Time : 3±0.5 sec Test Method: EIA-364-17B		Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-8	Salt Spray	Chamber Temperature : 35±2°C Air Tank Temperature : 47±1°C Salt Solution : 5 ± 0.5% Duration : 48 hours		Appearance	No Damage
100	our opray	Test Method: EIA-364-26B		Contact Resistance	\leq 40 m Ω
4-3-9	Temperature	5 cycles of : a) - 55 ±3°C b) +25 ±3°C	30 minutes 30 minutes	Appearance	No Damage
4-3-9	Cycling	c)+ 85 $\pm 2^{\circ}\!$	30 minutes	Contact Resistance	\leq 40 m Ω

5.INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimum.
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At 260±5°C peak shall be 10 seconds maximum.



6. 0.5mm FPC RETENTION FORCE SPEC

No of			on Force IN)	No of		Retention (MI	
CKT	UNIT	1 st	20 th	CKT	UNIT	1 st	20 th
	N	1.960	1.225		N	6.125	5.390
4	Kgf	0.200	0.125	21	Kgf	0.625	0.550
	N	2.205	1.470		N	6.370	5.635
5	Kgf	0.225	0.150	22	Kgf	0.650	0.575
	N	2.450	1.715		N	6.615	5.880
6	Kgf	0.250	0.175	23	Kgf	0.675	0.600
	N	2.695	1.960		N	6.860	6.125
7	Kgf	0.275	0.200	24	Kgf	0.700	0.625
	N	2.940	2.205		N	7.105	6.370
8	Kgf	0.300	0.225	25	Kgf	0.725	0.650
	N	3.185	2.450		N	7.350	6.615
9	Kgf	0.325	0.250	26	Kgf	0.750	0.675
	N	3.430	2.695		N	7.595	6.860
10	Kgf	0.350	0.275	27	Kgf	0.775	0.700
	N	3.675	2.940		N	7.840	7.105
11	Kgf	0.375	0.300	28	Kgf	0.800	0.725
	N	3.920	3.185		N	8.085	7.350
12	Kgf	0.400	0.325	29	Kgf	0.825	0.750
	N	4.165	3.430		N	8.330	7.595
13	Kgf	0.425	0.350	30	Kgf	0.850	0.775
	N	4.410	3.675		N	8.575	7.840
14	Kgf	0.450	0.375	31	Kgf	0.875	0.800
	N	4.655	3.920		N	8.820	8.085
15	Kgf	0.475	0.400	32	Kgf	0.900	0.825
	N	4.900	4.165		N	9.065	8.330
16	Kgf	0.500	0.425	33	Kgf	0.925	0.850
	N	5.145	4.410		N	9.310	8.575
17	Kgf	0.525	0.450	34	Kgf	0.950	0.875
	N	5.390	4.655		N	9.555	8.820
18	Kgf	0.550	0.475	35	Kgf	0.975	0.900
	N	5.635	4.900		N	9.800	9.065
19	Kgf	0.575	0.500	36	Kgf	1.000	0.925
	N	5.880	5.145		N	10.045	9.310
20	Kgf	0.600	0.525	37	Kgf	1.025	0.950

No of		Retention Force (MIN)		No of			on Force IN)
CKT	UNIT	1 st	10 th	CKT	UNIT	1 st	10 th
	N	10.290	9.555		N	12.740	12.005
38	Kgf	1.050	0.975	48	Kgf	1.300	1.225
	N	10.535	9.800		N	13.230	12.495
39	Kgf	1.075	1.000	50	Kgf	1.350	1.275
	N	10.780	10.045		N	15.680	14.945
40	Kgf	1.100	1.025	60	Kgf	1.600	1.525

FPC /FFC Connector Front Flip Lock Type Handling Precautions

This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

1. Common Handling Precautions

- Do not expose E&T's ZIF FPC/FFC connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's ZIF FPC/FFC connector, processing process product and processing product. Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please add a stiffener on the flexible printed circuit (FPC/FFC) when you mount the connector onto FPC in order to prevent deformation of the FPC/FFC.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.

2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).

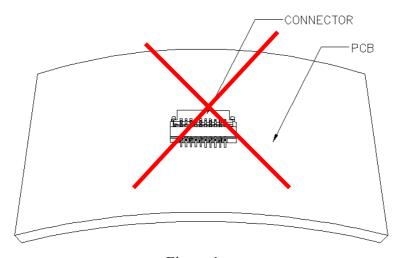


Figure 1.

3. Operation

FPC/FFC Insertion Procedure.

• 1) Connector installed on the board.

Lift up the actuator(Lock). Use thumb or index finger. (see figure 2).

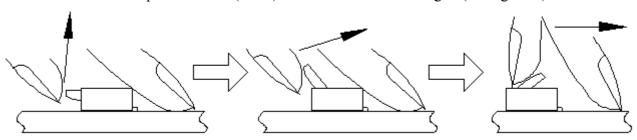


Figure 2.

• 2) Assure that the FPC/FFC is fully inserted parallel to mounting surface, with the exposed conductive traces facing down. (see figure 3).

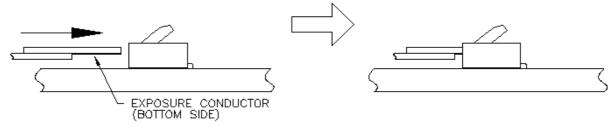


Figure 3.

• 3) Rotate down the actuator(Lock) until firmly closed. It is critical that the inserted FPC is not moved and remains fully inserted. Should the FPC be moved, open the actuator(Lock) and repeat the process, starting with Step 1(see figure 4).

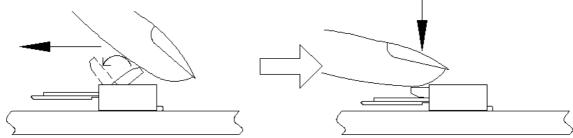


Figure 4.

FPC/FFC Removal.

1) Lift up the actuator(Lock). Carefully withdraw the FPC/FFC. (see figure 5).

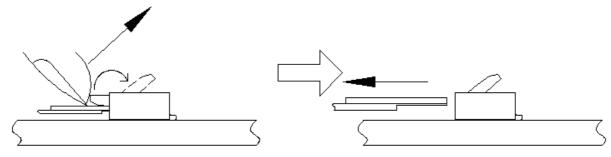


Figure 5.

4. Precautions When Inserting or Withdrawal FPC/FFC

• FPC/FFC to be insertion and withdrawal at an angle of about 15°, and the FPC/FFC should be inserted firmly all the way to the back. (see figure 6).

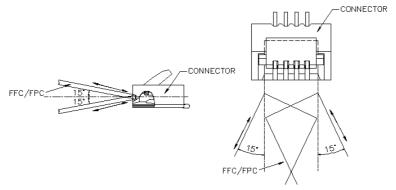


Figure 6.

- Do not apply excessive force or use any type of tool to operate the actuator(Lock).
- When locking the actuator(Lock), please make sure that the actuator is entirely closed by pressing on the entire actuator. Pushing the one specific point of the actuator may cause the actuator to be detached or damaged. When locking the longer actuator(Lock), please use two points to put pressure on locking. (see figure 7).

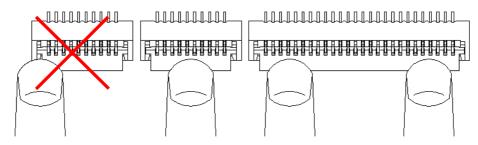
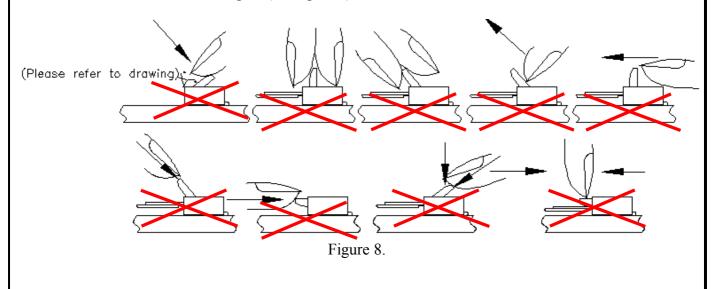


Figure 7.

- The connector will assure reliable performance when the actuator is open to an angle (please refer to drawing) maximum. Do not exceed this angle, as this may cause permanent damage to the connector. (see figure 8)
- Avoid grasping the actuator(Lock) with two fingers or lifting the actuator(Lock) with fingernail. (see figure 8)
- Do not apply force in the direction of arrows. Doing this may cause the actuator to be detached or damaged. (see figure 8).



• When inserting the FPC/FFC, do not forcefully rub against the surface beneath the connector insertion slot. Doing so will result in the FPC/FFC forcefully striking the contacts and this will cause contact deformation, peeling of the FPC/FFC conductors, and other irregularities. (see figure 9).

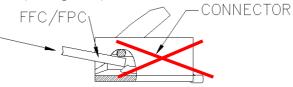
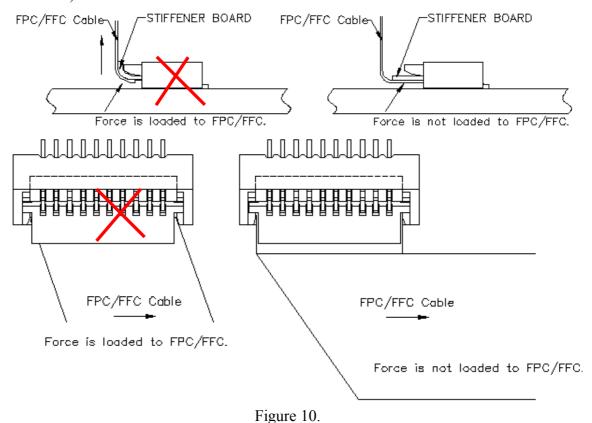


Figure 9.

- Do not apply any forces affecting soldered joints. Do not apply upward pull-force to the FPC/FFC close to the connector. (see figure 10).
- If necessary, please fix the FPC/FFC directly on the chassis. Also, please avoid pulling the FPC/FFC vertically or twisting the FPC back and force horizontally while it is inserted in the connector(see figure 10).
- Forming processing is conducted to FPC so as not to load force to connector. (see figure 10).



RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
A1	RE201108011	AUG-19-2011	Max	ADD Handing Precautions
A2	REN120509	MAY-15-2012	JIMMY	ADD 40 TYPE
A3	RE201305023	OCT-08-2013	Juno	Modify.
A4	REN140501	MAY-08-2014	Juno	Modify. P/N